



NOTES

1. ALL EXPOSED METALLIZED AREA SHALL BE GOLD PLATED .60 MICRO INCH MIN. THK. OVER NICKEL PLATED.
2. SEAL RING FLATNESS .005 MAX.
3. SEAL RING AND DIE ATTACH PAD ARE NOT GROUNDED TO A LEAD.

S=0
D=0

AN-20C

MULTIPLICATIONS	NAME	20LEAD CHIP CARRIER		TOLERANCES:	DATE: <i>[Signature]</i> CHECKED: <i>[Signature]</i> APPROVED: <i>[Signature]</i> 82-8-26	
	SCALE	10x		MATERIAL		±1% N.L.T ±.005
	DATE	CHG. NO.	REV.	APPROVED		
	CHANGE					KYOTO CERAMIC CO., LTD. KYOTO JAPAN

REF: LCC02035